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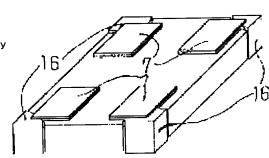
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(54) PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a printed wiring board and its manufacturing method; in which 1) the connection reliability of the terminal parts on the upper and lower surfaces of an interposer substrate is enhanced; 2) high density micro size terminals (lands) can be designed in order to provide a fine pitch small area electrode of an electronic component or element thus realizing high density mounting; and 3) at the contact hole of the terminals on the upper and lower surface, the efficiency of boring work is enhanced while reducing the cost by reducing works for boring a micro hole and decreasing the number of contact holes significantly. SOLUTION: As a contact part for electrically conducting the connection terminal part 7 on the upper surface of a printed wiring board and the external connection terminal part on the lower surface, a contact part 16 is formed on the side face or the corner of the printed wiring board by cutting the substantially central part of a non-through contact hole where the upper and lower faces of a filler filling a plated through hole is covered with a metal conductor.



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